WinWay *Your Trusted Partner in Semiconductor Testing*

TWSE:6515

穎崴科技股份有限公司

公司簡報

2026.10.19

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免責聲明

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公司簡介

成立日期

西元 2001 年 4 月 10 日

董事長兼總經理

王嘉煌

實收資本額

NTD 364,447,820

服務項目

半導體測試介面研發設計及製造銷售

員工人數

1602人

登記地址

高雄市楠梓區創意南路68號

高雄總公司



美國分公司

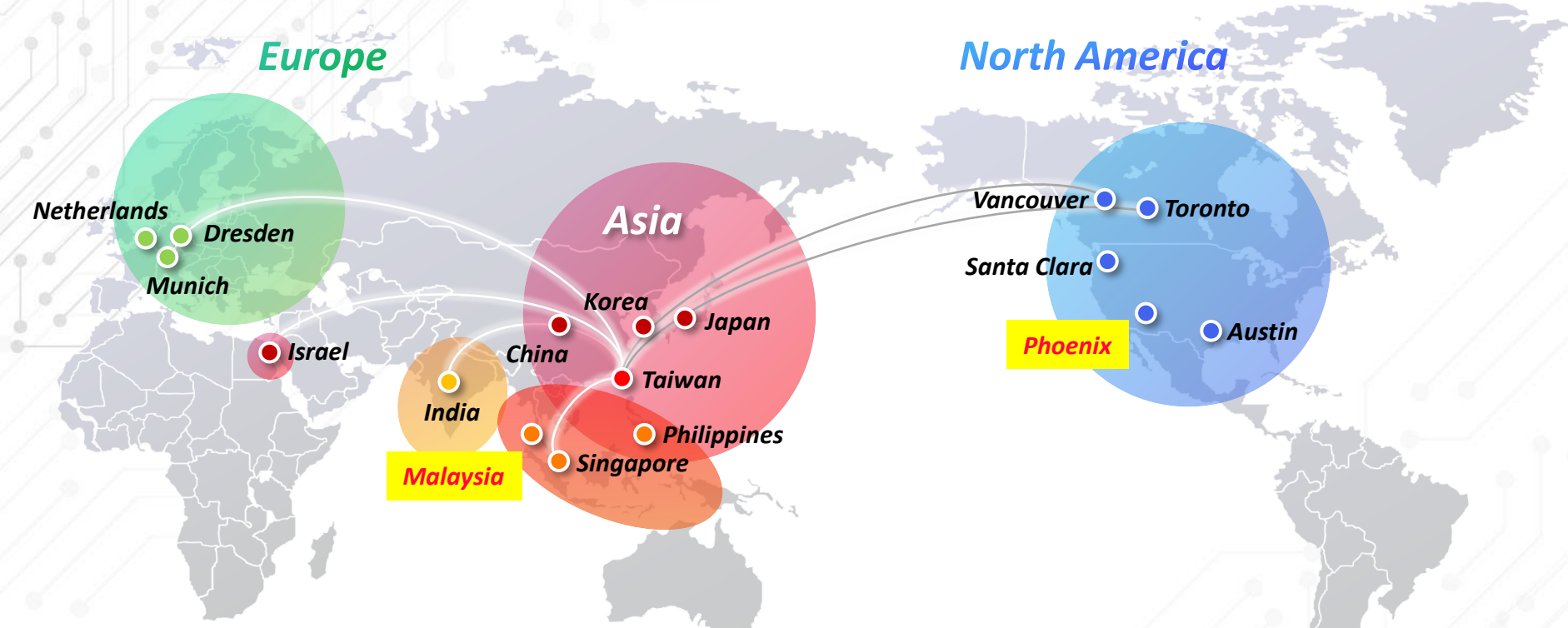


新竹分公司



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技術創新 服務全球



高雄探針廠	高雄廠	新竹廠	蘇州廠	仁武廠
Spring Probe for Socket	Coaxial Socket HyperSocket™	Vertical Probe Card MEMS Probe Card	Coaxial Socket	Coaxial Socket

WinWay

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高雄仁武廠 Socket產線加速擴增

仁武一廠

2026 年 5月 開始量產

仁武二廠

動土開工 2026 年 5 月 29 日

預計投產 2027 Q2

總面積約 6300坪



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自製探針產能持續擴充

成本優化

自製率提升，優化毛利結構

技術自主

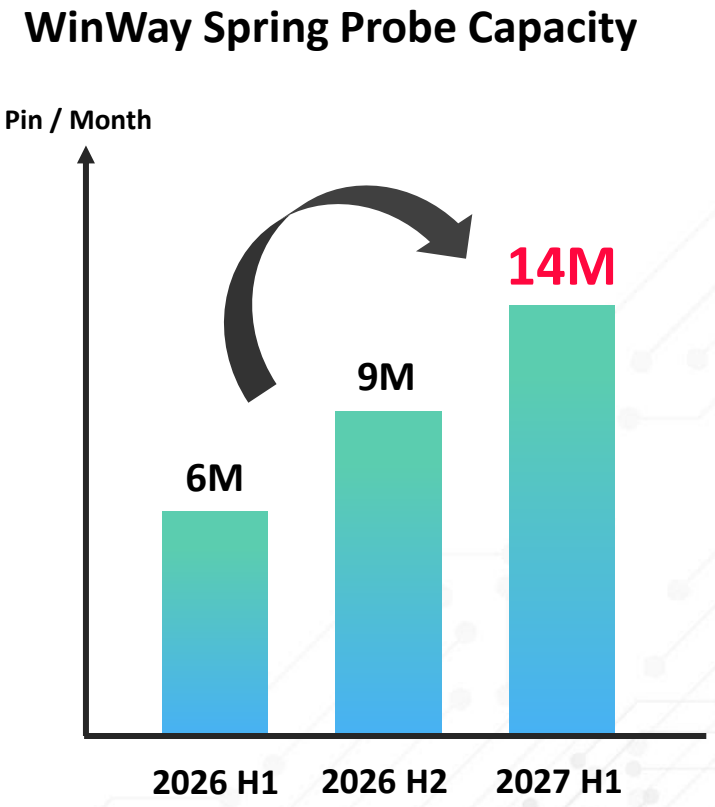
掌握關鍵製程技術，優化探針特性

品質控管

產品品檢嚴謹，卓越客戶體驗

交期彈性

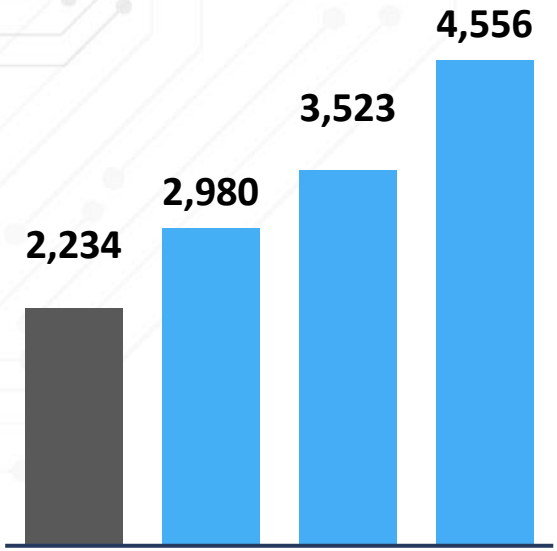
物料彈性調度，快速應變需求



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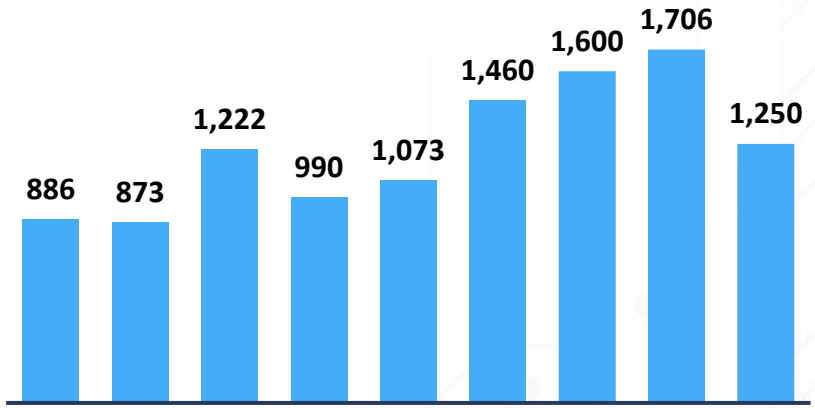
營收獲利持續成長

QUARTERLY REVENUE
(NTD MILLION)



	4Q25	1Q26	2Q26	3Q26
YoY	45%	30%	131%	153%
QoQ	24%	33%	18%	29%

MONTHLY REVENUE
(NTD MILLION)



	Jan-26	Feb-26	Mar-26	Apr-26	May-26	Jun-26	Jul-26	Aug-26	Sep-26
YoY	33%	-4%	69%	51%	120%	288%	156%	233%	88%
MoM	-5%	-2%	40%	-19%	8%	36%	10%	7%	-27%

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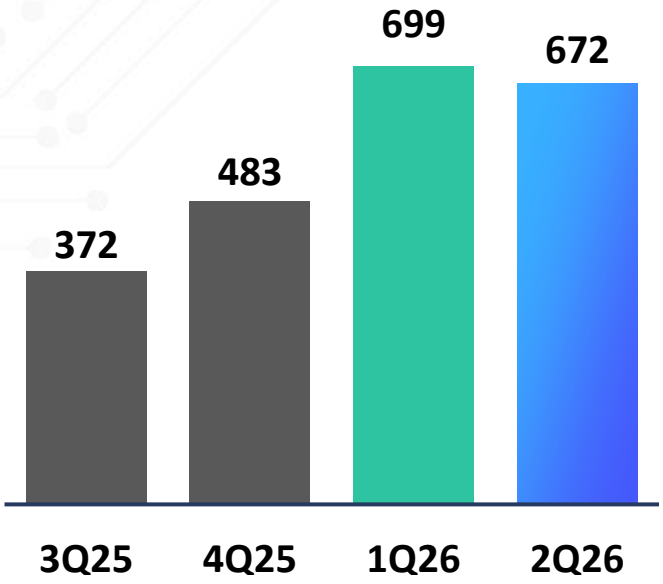
獲利及盈餘分配再創新高

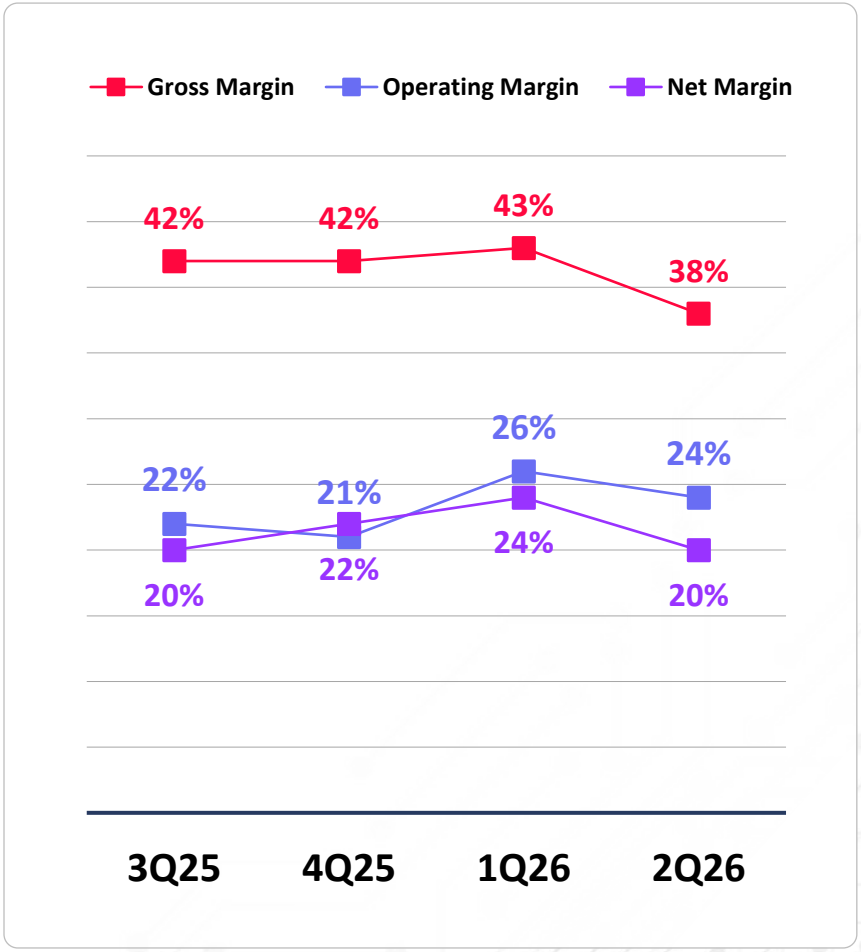
2026 Q1-Q2 EPS

(NT$) **38.24**

EPS	10.43	13.53	19.54	18.7

NET INCOME (NTD M)

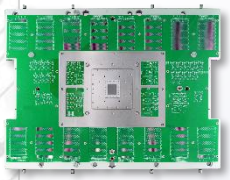




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2026產品組合

2026 H1



Probe Card

27 %



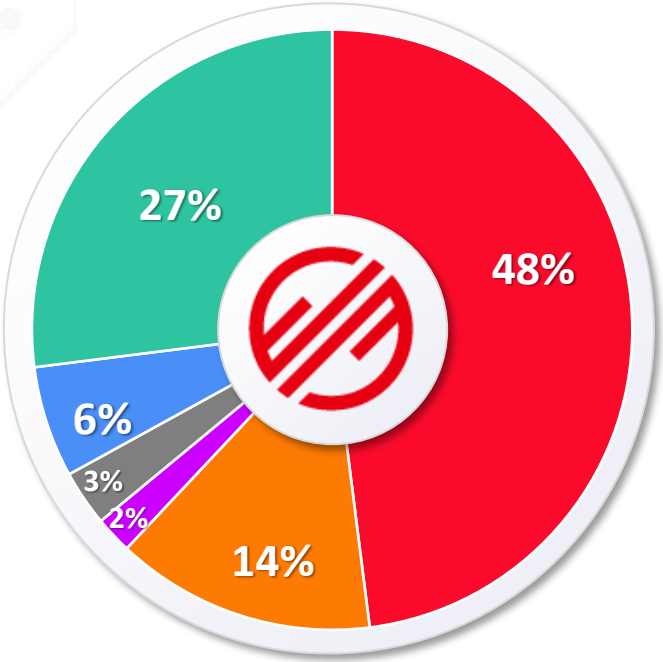
Contact Element

6 %



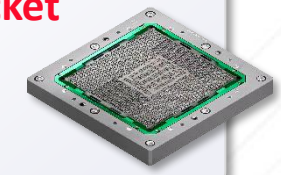
Others

3 %



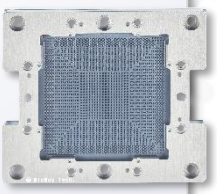
Coaxial Socket

48 %



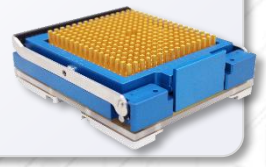
PoP & Plastic Socket

14 %



Burn-in Socket

2 %



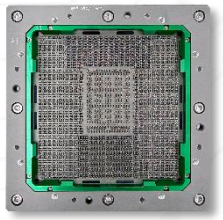
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產品應用廣泛

2026 H1



HyperSocket™



Coaxial Socket

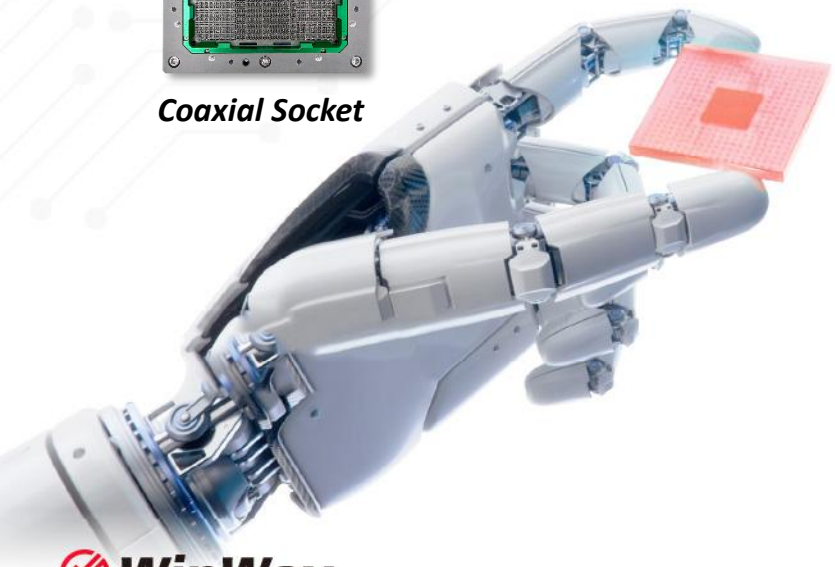
HPC & AI
70%



Networking
Auto / Others
18%
Plastic Socket

Smart Phone
8%
POP Plastic Socket

PC & Gaming
4%
POP Plastic Socket



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半導體多元應用驅動營收成長

CPU

TPU

GPU

AI ASIC

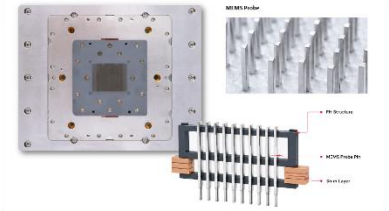
Automotive

Edge Computing

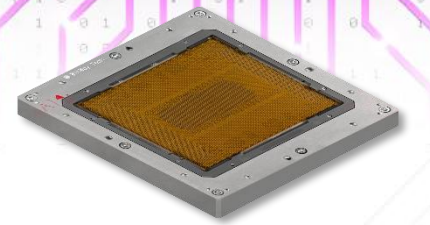
High Speed Networking

Smart Phone

Customer Approach



MEMS Probe Card



HyperSocket™



Functional Burn-in

WinWay

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高階測試座革新半導體測試方案

雙層超導 HyperSocket™

Patent NO.
TWI862047
TWI884802
TWI862191
TWI901161
TWI922268
TWI923382
CN220584352

Patent Pending
USA
Malaysia

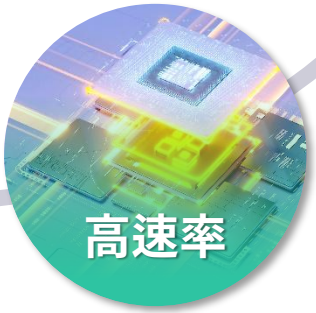




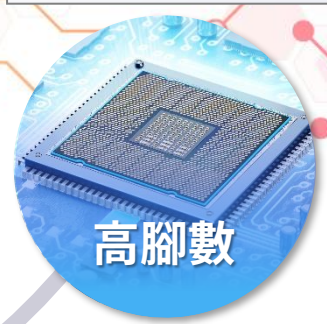
- 加大接觸面積
- 提升散熱效益
- 提高測試穩定性



- 平行電流路徑
- 大幅降低溫升



- 全金屬屏蔽，短迴路設計
- 滿足224Gbps以上測試



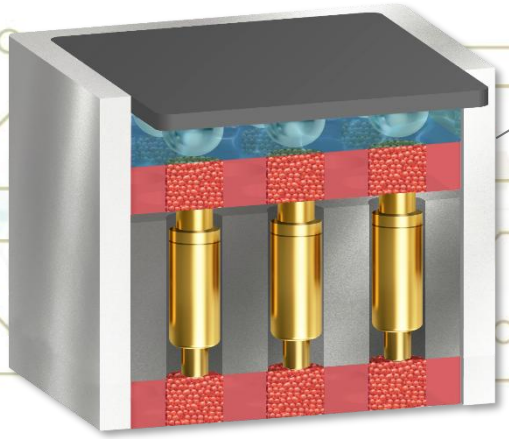
- 零預壓創新設計
- 延長維護週期

WinWay

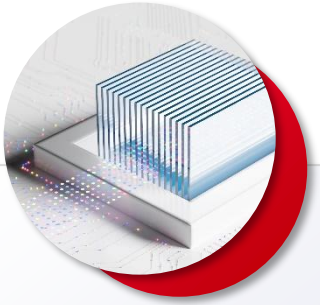
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全球首推半導體液冷測試方案

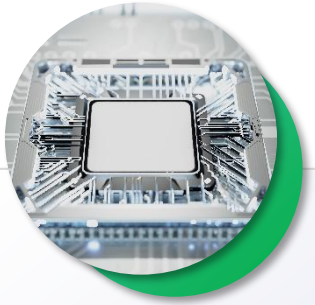
高電流液冷 Liquid Cooling Socket



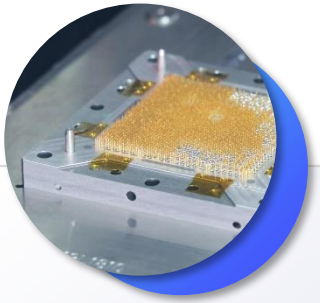
Patent NO.
TWI901181
US12625162



提升測試散熱效率



提高先進封裝測試穩定性



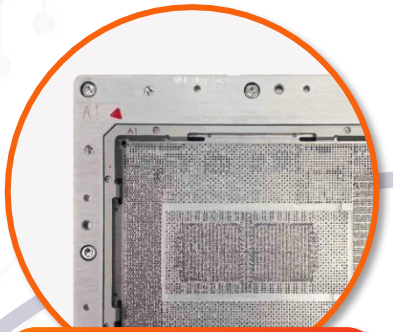
延長探針使用壽命

WinWay

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AI 持續帶動系統測試高速成長

Comprehensive solution for all test insertions



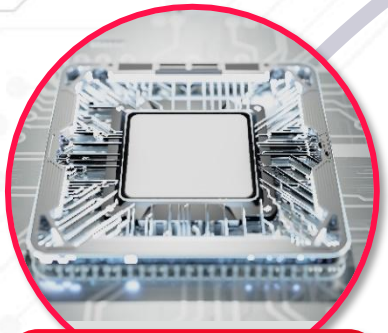
High Pin Count

>20KPin



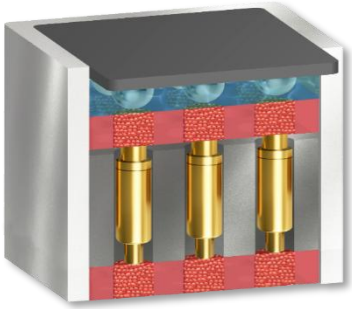
High-Speed Testing

>224Gbps



Ultra Large Package

>100X100mm^2

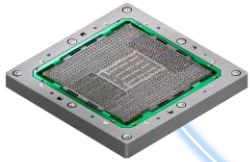


HyperSocket™

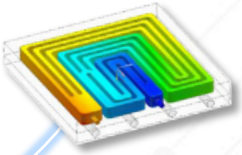


High Heat Density

>4000W



Coaxial Socket



Thermal System



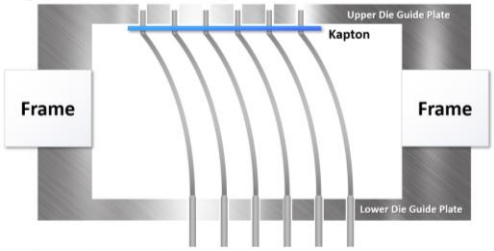
Functional Burn-in

WinWay

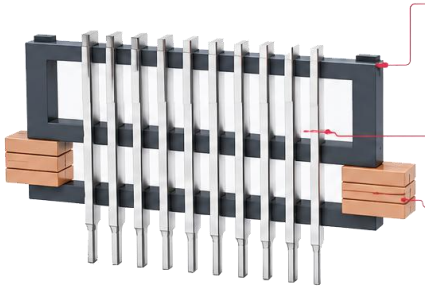
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晶圓測試將成IC測試挑戰

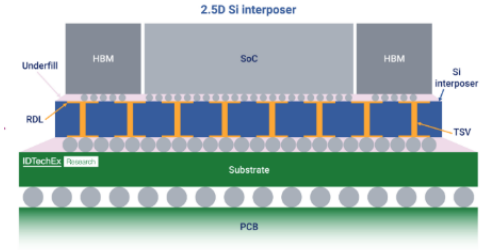
At Speed Test and K.G.D



Cobra



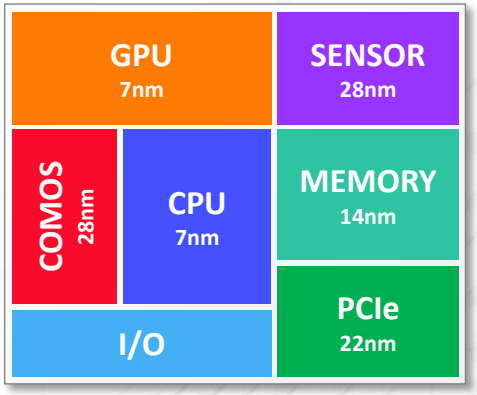
MEMS



Source : IDTechEx Research

Pin Count	Less, limited to probe force design	★ **Higher (More flexible to design)**
CCC(A)	2.2 @ 4mil probe diameter	★ **2.2 @ 3mil probe diameter**
High Speed	32G	★ **112G**
Force(g)	2~25	★ **1.5 ~ 4.5**
Pitch (um)	80~200	★ **40~200**
Operating Temp.	- 50℃ to 150℃	★ **- 50℃ to 175℃**

Chiplet **Multiple Probe Card Demand**



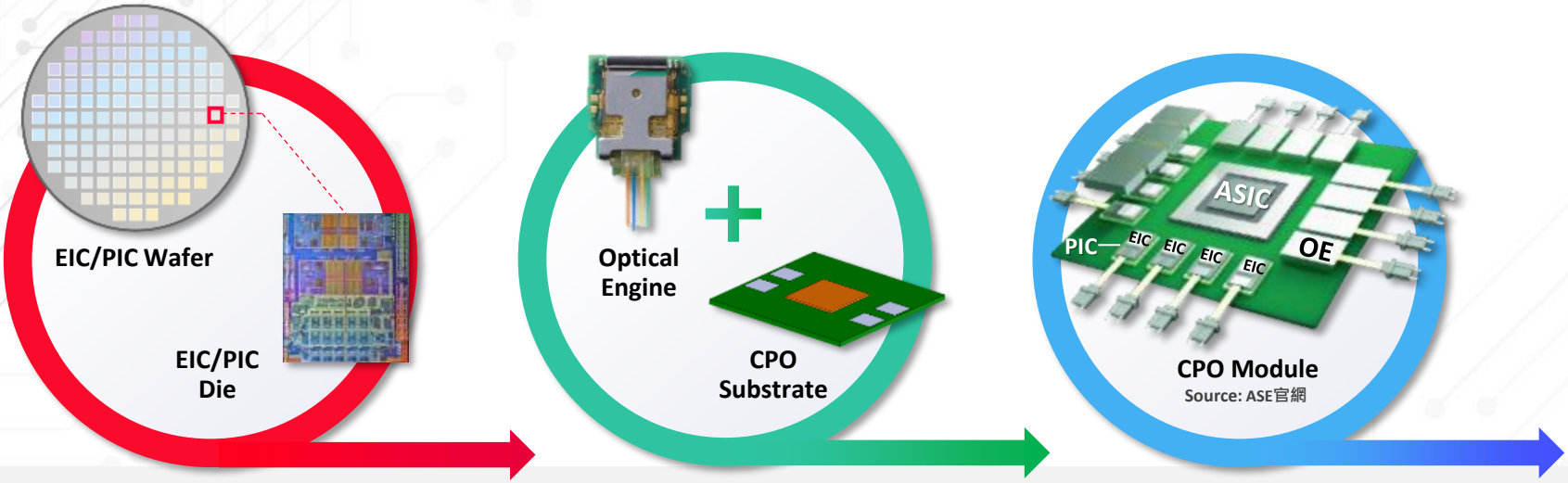
Source : Trend Force

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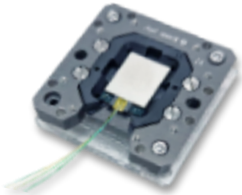
矽光子CPO測試方案全面導入

CPO 全域性測試架構

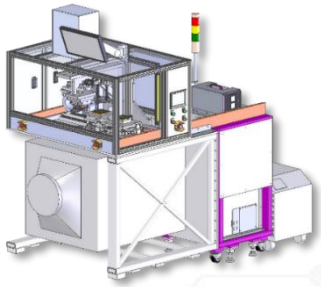




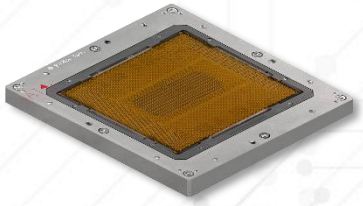
WLCSP Probe Head
(PIC & EIC Wafer test)



Optical and Electrical Test Socket
(Optical Engine)



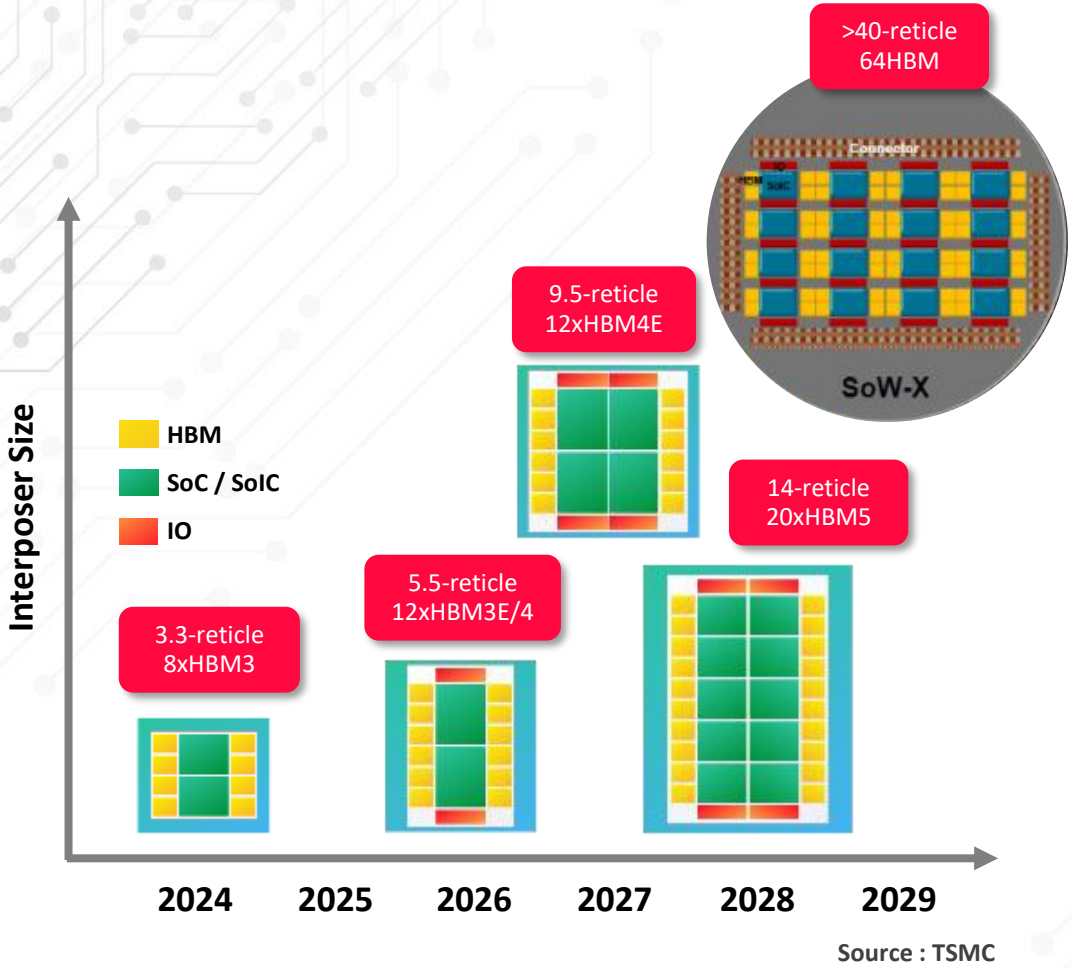
Double Sided Probing System



HyperSocket™

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Performance Breakthrough: Evolution of Advanced Packaging

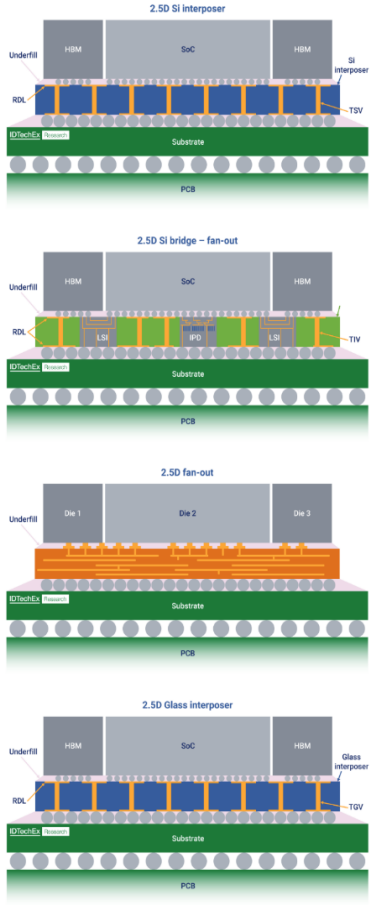


Source : TSMC

Si-based Interposer

Organic-based Interposer

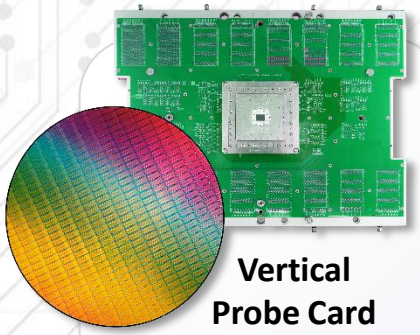
Glass-based Interposer



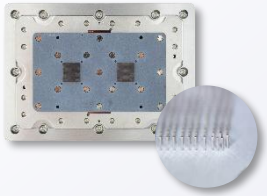
Source : IDTechEx Research

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Your Trusted Partner in Semiconductor Testing



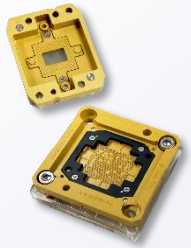
Vertical Probe Card



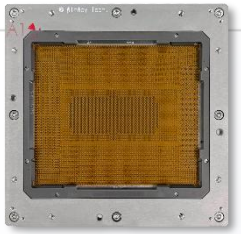
MEMS Probe Card



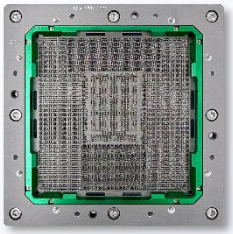
Coaxial Socket



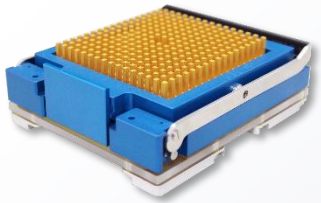
PoP Socket



HyperSocket™



Coaxial Socket





Production Burn-in Socket

Wafer Sort → **Final Test** → **SLT & SFT** → **Functional Burn-in**

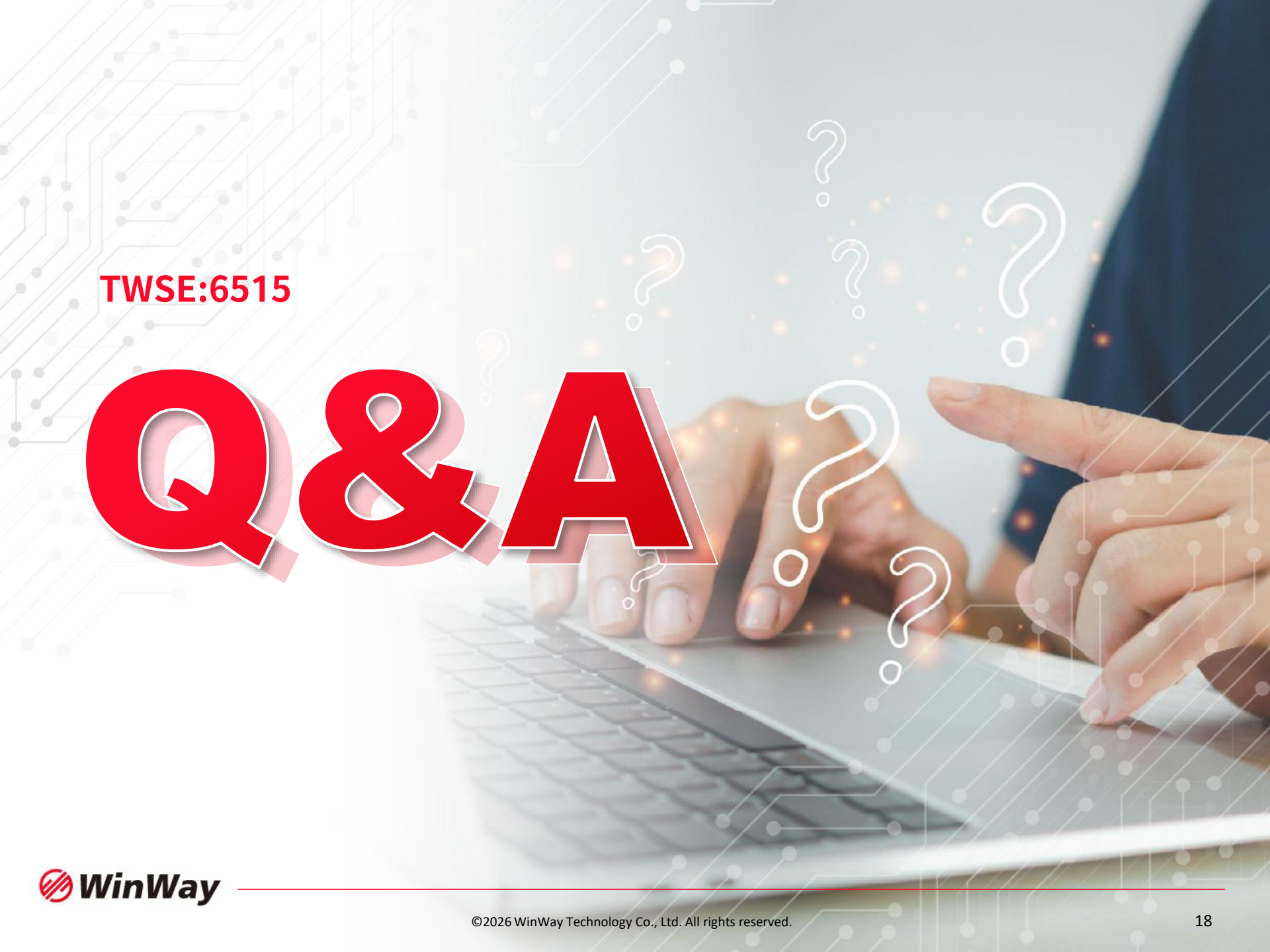
DFT Design For Testing **DFM** Design For Manufacturing

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Q&A



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THANK YOU

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